

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re the Application of:

JOAN K. VRTIS, ET AL.

Application No.:

Filed:

For: **Coated Heat Spreaders**

Art Group: 2835

Examiner: Tolin, Gerald P.

**INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In accordance with the duty of disclosure, enclosed is a copy of Information Disclosure Statement by Applicant (form PTO/SB/08), which is being submitted concurrently with the Divisional Application. It is respectfully requested that the cited references be considered and that the enclosed copy of PTO/SB/08 be initialed by the Examiner to indicate such consideration and a copy thereof returned to applicant(s). Some or all of the references listed on the enclosed PTO/SB/08 were previously identified in the parent application (Application No. 10/023,073, filed December 20, 2001) and copies of the references were furnished at that time. Accordingly, per 37 CFR §1.98(d)(1) additional copies of those references are not submitted herewith.

The submission of this Information Disclosure Statement is not to be construed as a representation that a search has been made in the subject application and is not to be construed as an admission that the information cited in this statement is material to patentability.

Please charge any fees due to Deposit Account 02-2666. A duplicate copy of the Fee Transmittal (PTO/SB/17) is enclosed for this purpose.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP



Heather M. Molleur, Reg. No. 50,432

Date:

3/11/04

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Examiner Signature		Date Considered	
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<sup>1</sup>Applicant's unique citation designation number (optional). <sup>2</sup>See Kinds Codes of USPTO Patent Documents at [www.uspto.gov](http://www.uspto.gov) or MPEP 901.04. <sup>3</sup>Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). <sup>4</sup>For Japanese patent documents, the indication of the year of reign of the Emperor must precede the serial number of the patent document. <sup>5</sup>Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup>Applicant is to place a check mark here if English language Translation is attached.

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Substitute for form 1449A/PTO <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>				<b>Complete if Known</b>	
				Application Number	
Sheet 2 of 3				Filing Date	
				First Named Inventor	Joan K. Vrtis
				Art Unit	2835
				Examiner Name	Tolin, Gerald P.
				Attorney Docket Number	42P13111D

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
		BATH, J., Selectron Corp., Lead Free Process Group Update, National Electronics Manufacturing Initiative, Jan. 17, 2001.	
		DEBIASE, JOSEPH D., Organic Solderability Preservatives: Benzotriazoles And Substituted Benzimidazoles, Enthone-OMI Inc., Conference Proceedings; Surface Mount International Conference, September 10, 1996, Abstract page downloaded from Surface Mount Technology Association, SMTA Headquarters - 5200 Willson Road, Suite 215, Edina, Minnesota 55424, 1 page.	
		DEBIASE, JOSEPH D., Organic Solderability Preservatives: Benzotriazoles And Substituted Benzimidazoles, Proceedings Of the SMTA, 1996, Enthone-OMI Inc., New Haven, Connecticut, pages 763-776.	
		HART, K., ET AL., DFE Study Gives Alternative Finishes the Green Light, PC FAB, Oct. 2000.	
		JOHNSON, R.W., ET AL, Thermal Cycle Reliability of Solder Joints to Alternate Plating Finishes, paper from Auburn University, 2000.	
		MORAWSKA, Z, ET AL., Lead-Free Solderability Preservative Coatings for PCBs, Advanced Microelectronics, v. 28, no. 3, May/June 2001.	
		PARQUET, D., ET AL., OSP: The High Performance Surface Finish, Electronic Interconnect Conference, 1997.	

Examiner Signature		Date Considered	
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\*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication.

<sup>1</sup>Applicant's unique citation designation number. <sup>2</sup>Applicant is to place a check mark here if English language Translation is attached.

Based on PTO/SB/08B (08-03) as modified by Blakely, Solokoff, Taylor & Zafman (wlr) 08/11/2003.  
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		ROMM, D., ET AL., Evaluation of Ni/Pd-Finished ICs with Lead Free Solder Alloys, Texas Instruments Application Report SZZA024, Jan. 2001.	
		SOLBERG, V., Impact of PCB Surface Finish on SMT Assembly Process Yield, Application Note from Tessera Corp.	
		SYED, A., Amkor Technology Corp., Surface Mount Requirements for Advanced Packaging Solutions, 2000.	
		WENGENROTH, KARL, ET AL., OSPS: Addressing Future Surface Finishing Needs, Enthone-OMI, Conference Proceedings, Surface Finishes Forum Conference, May 4, 2000, Abstract page downloaded from Surface Mount Technology Association, SMTA Headquarters - 5200 Willson Road, Suite 215, Edina, Minnesota 55424, 1 page.	
		Double Sided 4Mb SRAM Coupled Cap PBGA Card Assembly Guide, IBM Application Note, Feb. 1998.	
		Kester Solder Paste for Surface Mount and General Electronics Assemblies, Online Catalog of Preferred Products, 2001.	

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